

MCIMX537CVV8C2

End of Life

The part is being discontinued. Orders can be placed until the last time buy date. Shipments against last time buy orders are expected to be completed by the last time delivery date.

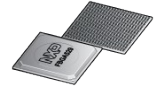
Features

i.MX53 32-bit MPU, ARM Cortex-A8 core, 800MHz, PBGA 529.

Package

FBGA529

FBGA529, plastic, fine-pitch ball grid array; 529 bumps; 0.8 mm pitch; 19 mm x 19 mm x 1.64 mm body.



- [Buy Options](#) | [Operating Characteristics](#) | [Environmental Information](#) | [Quality Information](#) | [Shipping Information](#) | [Discontinuance and Replacement](#) | [Product Change Notification](#)

Buy Options

MCIMX537CVV8C2

935318276557

End of Life

Last Buy Date: 15-Feb-2021

Last Delivery Date: 15-Jun-2021

[More Info](#)

TRAY-Tray, Bakeable, Multiple in Drypack

Min. Package Quantity: 84

Lead Time: 36 weeks

MCIMX537CVV8C2R2

935318276518

End of Life

Last Buy Date: 15-Feb-2021

Last Delivery Date: 15-Jun-2021

[More Info](#)

REEL-Reel 13" Q1/T1 in Drypack

Min. Package Quantity: 750

Lead Time: 36 weeks

1K @ US

Operating Characteristics

No information available

Environmental Information

Material Declaration	Pb-Free	EU RoHS	Halogen Free	RHF Indicator	2nd Level Interconnect	REACH SVHC	Weight (mg)
MCIMX537CVV8C2(935318276557)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	e2	REACH SVHC	2136.1
MCIMX537CVV8C2R2(935318276518)	Yes	Yes Certificate Of Analysis (CoA)	Yes	D	e2	REACH SVHC	2136.1

Quality Information

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
	No	3	260	40

Material Declaration	Safe Assure Functional Safety	Moisture Sensitivity Level (MSL)	Peak Package Body Temperature (PPT) (C°)	Maximum Time at Peak Temperatures (s)
		Lead Free Soldering	Lead Free Soldering	Lead Free Soldering
(935318276557)				
MCIMX537CVV8C2R2 (935318276518)	No	3	260	40

Shipping Information

Part Number	Harmonized Tariff (US) Disclaimer	Export Control Classification Number (US)	CCATS
MCIMX537CVV8C2 (935318276557)	854231	5A992C	G166378
MCIMX537CVV8C2R2 (935318276518)	854231	5A992C	G166378

Discontinued and Replacement Part Data

Part Number / 12NC	Discontinuance Notice	Last Time Buy Date	Last Time Delivery Date	Replacement
MCIMX537CVV8C2 (935318276557)	NOTICE	2021-02-15	2021-06-15	MCIMX537CVP8C2 (935420974557)
MCIMX537CVV8C2R2 (935318276518)	NOTICE	2021-02-15	2021-06-15	MCIMX537CVP8C2R2 (935420974518)

Product Change Notification

Part Number / 12NC	Issue Date	Effective Date	PCN	Title
MCIMX537CVV8C2 (935318276557)	2021-02-20	2021-02-21	202102018DN	Non-Auto i.MX53 PBGA Part Number Migration due to Molding Change from Corner-Gate Mold (CGM) to Pin-Gate Mold (PGM)
MCIMX537CVV8C2R2 (935318276518)				
MCIMX537CVV8C2 (935318276557)	2020-12-15	2020-12-16	202011011I	NXP Will Add a Sealed Date to the Product Label
MCIMX537CVV8C2R2 (935318276518)				
MCIMX537CVV8C2 (935318276557)	2017-12-20	2018-01-03	201710023I	New PQ Label Input for Non-MPQ Shipments
MCIMX537CVV8C2R2 (935318276518)				



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